

**Product Change Notification - GBNG-17MPXE629**


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**Date:**

24 Oct 2018

**Product Category:**

16-Bit - Microcontrollers and Digital Signal Controllers

**Affected CPNs:**

**Notification subject:**

CCB 3465 Final Notice: Qualification of G631HQ mold compound material in selected products of 160K wafer technology available in 64L TQFP (14x14x1 mm) package using 354x354 mils lead frame paddle size at ANAP assembly site.

**Notification text:**
**PCN Status:**

Final notification.

**PCN Type:**

Manufacturing Change

**Microchip Parts Affected:**

Please open one of the icons found in the Affected CPNs section above.

NOTE: For your convenience Microchip includes identical files in two formats (.pdf and .xls).

**Description of Change:**

Qualification of G631HQ mold compound material in selected products of 160K wafer technology available in 64L TQFP (14x14x1 mm) package using 354x354 mils lead frame paddle size at ANAP assembly site.

**Pre Change:**

Using G700L mold compound and 374x374 mils lead frame paddle size.

**Post Change:**

Using G361HQ mold compound and 354x354 mils lead frame paddle size.

**Pre and Post Change Summary:**

	<b>Pre Change</b>	<b>Post Change</b>
<b>Assembly Site</b>	Amkor Technology Philippine (P1/P2), INC. (ANAP)	Amkor Technology Philippine (P1/P2), INC. (ANAP)
<b>Wire material</b>	Au	Au
<b>Die attach material</b>	3230	3230
<b>Molding compound material</b>	G700L	G631HQ
<b>Lead frame material</b>	C194	C194
<b>Lead frame paddle size</b>	374 x 374 mils	354 x 354 mils

**Impacts to Data Sheet:**

None

**Change Impact:**

None

**Reason for Change:**

To improve productivity by qualifying G361HQ mold compound material.

**Change Implementation Status:**

In Progress



**Estimated First Ship Date:**

November 24, 2018 (date code: 1847)

NOTE: Please be advised that after the estimated first ship date customers may receive pre and post change parts.

**Time Table Summary:**

	July 2018					October 2018				November 2018				
Workweek	27	28	29	30	31	40	41	42	43	44	45	46	47	48
Initial PCN Issue Date			X											
Qual Report Availability									X					
Final PCN Issue Date									X					
Estimated Implementation Date													X	

**Method to Identify Change:**

Traceability code

**Qualification Report:**

Please open the attachments included with this PCN labeled as PCN\_#\_Qual Report.

**Revision History:**

**July 20, 2018:** Issued initial notification.

**October 24, 2018:** Issued final notification. Attached the Qualification Report. Provided estimated first ship date on November 24, 2018.

The change described in this PCN does not alter Microchip's current regulatory compliance regarding the material content of the applicable products.

**Attachment(s):**

[PCN\\_GBNG-17MPXE629\\_Qual\\_Report.pdf](#)

Please contact your local [Microchip sales office](#) with questions or concerns regarding this notification.

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Affected Catalog Part Numbers(CPN)

DSPIC30F6011-20E/PF

DSPIC30F6011-20I/PF

DSPIC30F6011-30I/PF

DSPIC30F6012-20I/PF

DSPIC30F6012-30I/PF